Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	10/709999	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 06:47
L2	0	2005/0020076	US-PGPUB; USPAT; USOCR; EPO; JPO	OR.	ON	2006/08/25 06:48
L3	1	"20050020076"	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 06:51
L4	1	"20040043526"	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 06:53
L5	3233325	"20040223267" A1	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 06:53
L6	2	"20040223267"	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 06:55
L7	1	"20040084400"	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 07:01
L8	6	("20020036876" "20020142192" "534 6841" "6083794" "6452764" "6759263 ").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 07:01
L9	53	("20020036876" "20020142192" "534 6841" "6083794" "6452764" "6759263 ")	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 07:03

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L10	40	("0009616" "0048127" "20030198113" "20030198113" "0181056" "2004000	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 07:03
L11	362	("0009616" "0048127" "20030198113" "20030198113" "0181056" "2004000 1350" "20040001350" "20040043526" "20040051522" "20040051522" "200 40084400" "20040252559" "20040253437" " 20050020076" "20050050399" "20050 050399" "20050079647" "2005007964 7" "20050079683" "20050079683" "20 050087519" "2005008887519" "2005008 8875" "20050088875" "20050102581" "20050102581" "20050127418" "200 50127418" "20050151552" "20050151 552" "20050185458" "20050185458" " 4619872" "5792569" "5946228" "6034 887" "6072718" "6104633" "6299991" "6299991" "6333067" "6333067" "63 85082" "6385082" "6452764" "645276 4" "6538919" "6538919" "6660568" "6 660568" "6784091" "6784091" "68121 41" "6812141" "6365419" "6495275" "	US-PGPUB; USPAT; USOCR; EPO; JPO	OR .	ON	2006/08/25 07:04
L12	402	11 or 9	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 07:04
L13	23	12 and ((mask hardmask) near3 (metal conductive))	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 07:19

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L14	259	("MTJ" magnetic ajd tunnel adj junction) and ((mask hardmask) near3 (metal conductive)) with (conductive near3 line wiring wire)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 07:22
L15	0	12 and ((pinned free) near3 layer) with ("MTJ" magnetic ajd tunnel adj junction) and ((mask hardmask) near3 (metal conductive)) with (conductive near3 line wiring wire)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 07:23
L16	34	14 and ((pinned free) near3 layer) with ("MTJ" magnetic ajd tunnel adj junction)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 07:24
S40	1435	(magnetic adj tunnel adj junction "MTJ" "MRAM" (magnetoresistive magneto adj resistive) near3 memory) with (free pinned) near3 (layer film)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/17 12:24
S41	894	S40 and barrier with (free pinned) near3 (layer film)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/17 12:25
S42	75	S41 and (mask\$3 hardmask\$3) same barrier with (free pinned) near3 (layer film)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/17 13:34
S43	1435	(magnetic adj tunnel adj junction "MTJ" "MRAM" (magnetoresistive magneto adj resistive) near3 memory) with (free pinned) near3 (layer film)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/17 13:35
S44	894	S43 and barrier with (free pinned) near3 (layer film)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/17 14:10
S45	75	S44 and (mask\$3 hardmask\$3) same barrier with (free pinned) near3 (layer film)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/17 13:35
S46	3	S45 and (free) near3 (layer film) with (inacti\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/17 13:37
S47	5	S44 and free with inact\$4	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/17 13:58
S48	580	S44 and free with resist\$4	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/17 13:58

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S49	1022	S43 and (barrier nonmagnetic insulator) with (free pinned) near3 (layer film)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/17 14:15
S50	10	S49 and (free) near3 (layer film) with convers\$4	US-PGPUB; USPAT; USOCR; EPO; JPO	OR .	ON	2006/04/17 14:11
S51	82	S43 and (barrier nonmagnetic insulator) with (free pinned) near3 (layer film) same (mask\$3 hardmask\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/17 14:29
S52	1	10/709999	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/17 14:23
S53	318	S43 and (barrier nonmagnetic insulator) with (free pinned) near3 (layer film) and (mask\$3 hardmask\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/17 14:30
S54	281	S53 and (free) near3 (layer film) and (mask\$3 hardmask\$3 hard nwae3 mask\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/17 14:32
S55	281	S53 and (free) near3 (layer film) and (mask\$3 hardmask\$3 hard near3 mask\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/18 08:19
S56	38	S55 and (free mask\$3 hardmask\$3 hard near3 mask\$3) with (oxidation oxidizing oxioxidization oxidized)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/18 10:31
S57	2	10/283348	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/08/25 06:35
S58	2	((free) near3 (layer film)) with (mask\$3 hardmask\$3 hard near3 mask\$3) with anodi\$4	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/18 08:21
S59	0	((free adj layer)) with (mask\$3 hardmask\$3 hard near3 mask\$3) with (anodi\$4 anodization)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/18 08:21
S60	5	((free adj layer)) with (anodi\$4 anodization)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/18 08:22

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S61	240	sputtering with (method process) and (plasma near3 bombardment) with (method process)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/18 10:33
S62	76	sputtering with (method process) same (plasma near3 bombardment) with (method process)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/18 10:34
S63	88	sputtering with (method process) and (plasma near3 bombardment) with (method process) and (planarization planarizing planar\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/18 10:37
S64	29	sputtering near3 (method process) and (plasma near3 bombardment) near3 (method process) and (planarization planarizing planar\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/18 10:41
S65	9	sputtering near3 (method process) and (plasma near3 bombardment) near3 (method process) same (planarization planarizing planar\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/18 10:44
S66	9	(sputtering near3 (method process) and (plasma near3 bombardment) near3 (method process)) same (planarization planarizing planar\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/18 10:44
S67	1	(sputtering near3 (method process) and (plasma near3 bombardment) near3 (method process)) with (planarization planarizing planar\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/04/18 10:45